



Part Number:		AS4C16M16SA-7BCN / 6BIN / 6BAN							
Part Weight:		130.213mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL-832NX / AUS 308	36.968	Bismaleimide Triazine resin	105391-33-1	6.99%	2.586	1.98	69948
				Epoxy resin -1	25722-66-1	6.99%	2.586	1.98	69948
				Epoxy resin -2	9003-36-5	6.99%	2.586	1.98	69948
				Inorganic Filler	21645-51-2	15.74%	5.818	4.46	157383
				Continuous Filament Fiber Glass	65997-17-3	21.57%	7.973	6.11	215673
				Talc containing no asbestiform fibers	14807-96-6	0.45%	0.166	0.13	4492
				Morpholine derivative	Trade secret	0.45%	0.166	0.13	4492
				Barium sulfate	7727-43-7	5.05%	1.868	1.43	50535
				Silica, amorphous	7631-86-9	0.11%	0.042	0.03	1123
				Dipropylene glycol monomethyl ether	34590-94-8	2.70%	0.996	0.76	26952
				Epoxy resin A	Trade secret	1.46%	0.540	0.41	14599
				Epoxy resin B	85954-11-6	1.01%	0.374	0.29	10107
				Copper	7440-50-8	29.79%	11.013	8.45	297900
				Nickel	7440-02-0	0.61%	0.226	0.17	6100
Gold	7440-57-5	0.08%	0.030	0.02	800				
2	Mold compound	G1250	72.967	Epoxy resin	Trade Secret	5.50%	4.013	3.09	55000
				Phenol resin	Trade Secret	4.50%	3.284	2.52	45000
				Carbon Black	1333-86-4	0.30%	0.219	0.17	3000
				Silica Fused	60676-86-0	89.70%	65.451	50.32	897000
3	Epoxy	2025D	0.274	Silica, amorphous, fused	Trade Secret	54.50%	0.149	0.11	545000
				Bismaleimide monomer	Trade Secret	27.50%	0.075	0.06	275000
				Acrylate monomer	Trade Secret	7.50%	0.021	0.02	75000
				Epoxy Resin	Trade Secret	7.50%	0.021	0.02	75000
				Acrylic resin	112-15-2	3.00%	0.008	0.01	30000
4	Solder Ball	96.5Sn3Ag0.5Cu	15.909	Tin	7440-31-5	96.50%	15.352	11.77	965000
				Silver	7440-22-4	3.00%	0.477	0.37	30000
				Copper	7440-50-8	0.50%	0.080	0.06	5000
5	Gold wire	Au	0.548	Gold	7440-57-5	100.00%	0.548	0.42	1000000
6	Die	Chip	3.547	Silicon	7440-21-3	98.00%	3.476	2.67	980000
				Aluminum	7429-90-5	2.00%	0.071	0.05	20000

130.213

600.00%

130.213

100.00

6000000